

# N-Channel 200-V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>(BR)DSS</sub> (V)	<b>R<sub>DS(on)</sub> (</b> Ω)	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)			
200	0.038 at V <sub>GS</sub> = 15 V	45	57			
200	0.043 at V <sub>GS</sub> = 10 V	40	57			

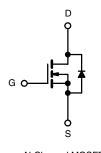
#### **FEATURES**

- TrenchFET<sup>®</sup> Power MOSFETS
- 175 °C Junction Temperature
- 100 %  $R_g$  and UIS Tested

## **APPLICATIONS**

- Power Supply
- Lighting Systems





N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b>	T <sub>A</sub> = 25 °C, unless oth	erwise noted			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V <sub>DS</sub>	200	v	
tate-Source Voltage $T_{\rm C} = 25 ^{\circ}{\rm C}$		V <sub>GS</sub>	± 25	v	
Continuous Drain Current ( $T_J = 175 \ ^{\circ}C$ )			45		
	T <sub>C</sub> = 100 °C	I <sub>D</sub>	26		
Pulsed Drain Current		I <sub>DM</sub>	150	A	
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	20		
Single Pulse Avalanche Energy <sup>a</sup>	L = 0.11111	E <sub>AS</sub>	20	mJ	
	T <sub>C</sub> = 25 °C	P	166 <sup>b</sup>	14/	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C <sup>c</sup>	– P <sub>D</sub> –	3.12	W	
Operating Junction and Storage Temperature Ra	inge	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient (PCB Mount) <sup>c</sup>	R <sub>thJA</sub>	40	°C/W		
Junction-to-Case (Drain)	R <sub>thJC</sub>	0.75			

Notes:

a. Duty cycle  $\leq$  1 %.

b. See SOA curve for voltage derating.

c. When Mounted on 1" square PCB (FR-4 material).



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$	200			4.5 V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2.5		4.5		
Coto Porte Laskana		$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	- nA	
Gate-Body Leakage	IGSS	$V_{DS} = 0 V, V_{GS} = \pm 25 V$			± 300		
		$V_{DS} = 200 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 200 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 100 ^{\circ}\text{C}$			25	μΑ	
		$V_{DS} = 200 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 150 ^{\circ}\text{C}$			250		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10$ V, $V_{GS} = 10$ V	40			Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.038		+	
	Р	V <sub>GS</sub> = 15 V, I <sub>D</sub> = 20 A		0.043		-	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS}$ = 10 V, $I_{D}$ = 20 A, $T_{J}$ = 100 °C		0.088		Ω	
		$V_{GS}$ = 10 V, $I_{D}$ = 20 A, $T_{J}$ = 150 °C		0.120			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A	25			S	
Dynamic <sup>b</sup>	•			+			
Input Capacitance	C <sub>iss</sub>			3100		pF	
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz		300			
Reverse Transfer Capacitance	C <sub>rss</sub>			135			
Tatal Cata Charge	Qg	$V_{DS} = 100 \text{ V}, V_{GS} = 15 \text{ V}, I_{D} = 50 \text{ A}$		85	127		
Total Gate Charge <sup>c</sup>				57	85	nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS}$ = 100 V, $V_{GS}$ = 10 V, $I_{D}$ = 50 A		14			
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			20			
Gate Resistance	Rg	f = 1 MHz		1.2	1.8	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			16	25		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 100 V, $R_L$ = 2 $\Omega$		170	260	20	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$\rm I_D \cong 50$ A, $\rm V_{GEN}$ = 10 V, $\rm R_g$ = 1 $\Omega$		27	42	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			9	18	1	
Source-Drain Diode Ratings and Cha	aracteristics 7	「 <sub>C</sub> = 25 ℃					
Continuous Current	ا <sub>S</sub>	Is			36		
Pulsed Current	I <sub>SM</sub>			1	80	A	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 20 A, V <sub>GS</sub> = 0 V		0.86	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			116	175	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>			9	14	Α	
Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = 40 A, di/dt = 100 A/μs		0.53	0.8	μC	
Reverse Recovery Fall Time	t <sub>a</sub>			84			
Reverse Recovery Rise Time	t <sub>b</sub>			32		nS	

Notes:

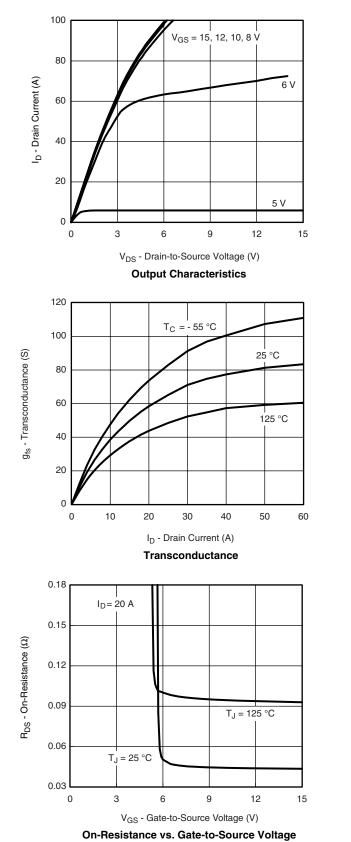
a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

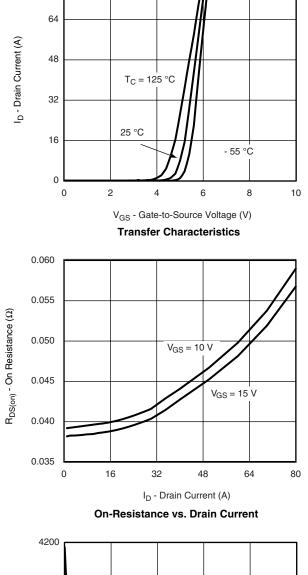
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

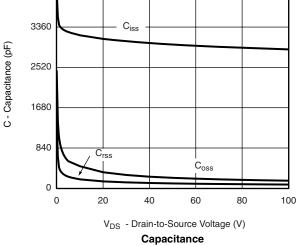




#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

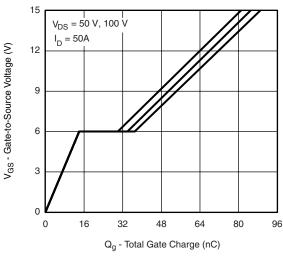


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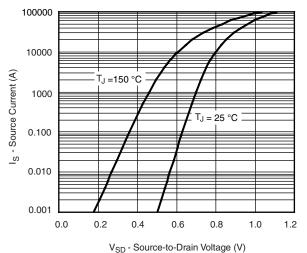


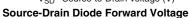


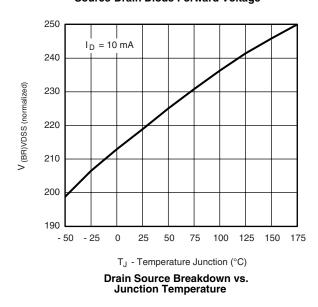


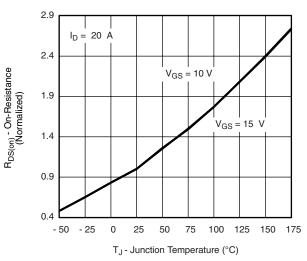




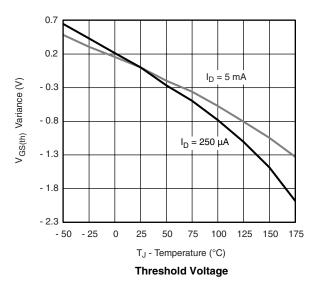


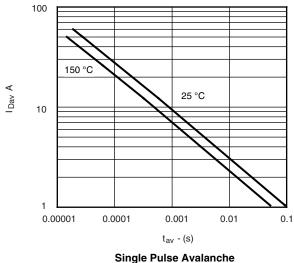


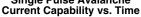




**On-Resistance vs. Junction Temperature** 

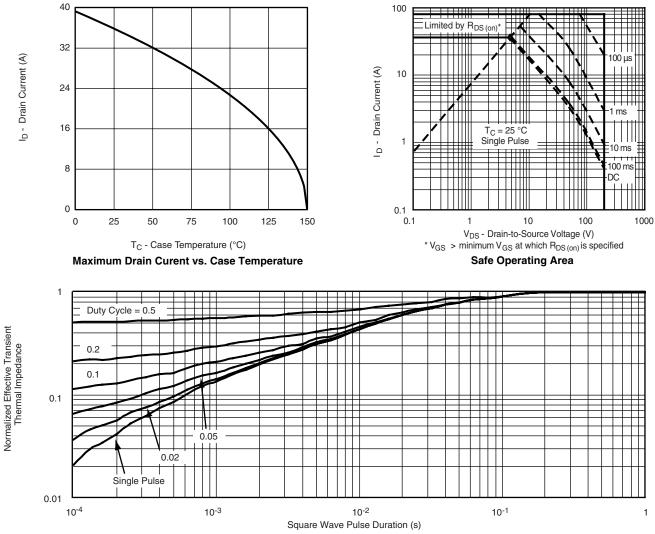








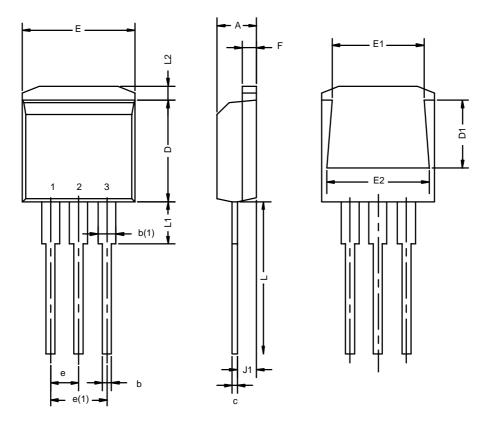
#### **THERMAL RATINGS**



Normalized Thermal Transient Impedance, Junction-to-Case



### TO-262: 3-LEAD



	<b>MILLIMETERS</b> *		INCHES		
Dim	Min	Max	Min	Мах	
Α	4.32	4.70	0.170	0.185	
b	0.64	1.00	0.025	0.039	
b(1)	1.14	1.40	0.045	0.055	
С	0.36	0.50	0.014	0.020	
D	8.64	9.65	0.340	0.380	
D1	5.59	6.10	0.220	0.240	
е	2.41	2.67	0.095	0.105	
e(1)	4.95	5.33	0.195	0.210	
E	10.03	10.41	0.395	0.410	
E1	7.87	8.64	0.310	0.340	
E2	9.02	9.53	0.355	0.375	
F	1.14	1.40	0.045	0.055	
J1	2.41	2.79	0.095	0.110	
L	13.08	14.22	0.515	0.560	
L1	-	3.81	-	0.150	
L2	1.02	1.40	0.040	0.055	
ECN: T-02234—Rev. C, 14-Oct-02 DWG: 5855					

 $^{\ast}\mbox{Use}$  millimeters as the primary measurement



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